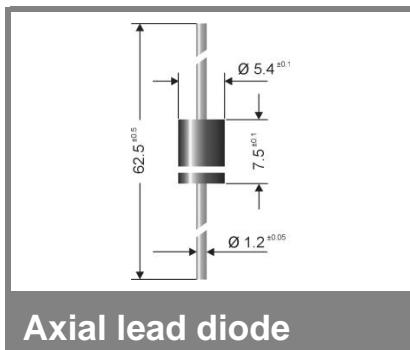


SBH 820 ... SBH 845



Axial lead diode

Type	Repetitive peak reverse voltage V_{RRM} V	Surge peak reverse voltage V_{RSM} V	Max. reverse recovery time $I_F = -A$ $I_R = -A$ $I_{RR} = -A$ t_{rr} ns	Max. forward voltage V_F ²⁾
SBH 820	20	20	-	0,53
SBH 830	30	30	-	0,53
SBH 840	40	40	-	0,53
SBH 845	45	45	-	0,53

High temperature schottky barrier diodes

SBH 820 ... SBH 845

Forward Current: 8 A

Reverse Voltage: 20 to 45 V

Preliminary Data

Features

- Max. solder temperature: 260°C
- Plastic material has UL classification 94V-0

Mechanical Data

- Plastic case: 5,4 x 7,5 [mm]
- Weight approx.: 1,4 g
- Terminals: plated terminals solderable per MIL-STD-750
- Mounting position: any
- Standard packaging: 1250 pieces per ammo or per reel

1) Valid, if leads are kept at T_A at a distance of 10 mm from case

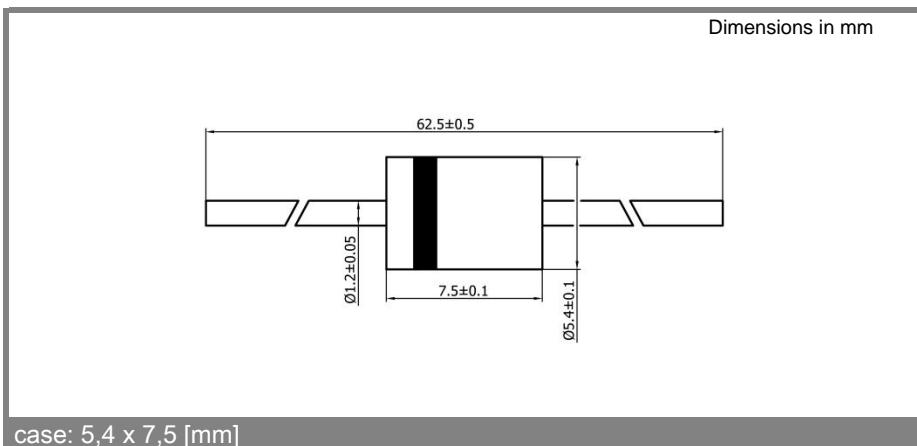
2) $I_F = 5$ A, $T_j = 25$ °C

3) $T_A = 25$ °C

4) Thermal resistance from junction to lead/terminal at a distance 0 mm from case

Absolute Maximum Ratings		$T_A = 25$ °C, unless otherwise specified	
Symbol	Conditions	Values	Units
I_{FAV}	Max. averaged fwd. current, R-load, $T_A = 50$ °C ¹⁾	8	A
I_{FRM}	Repetitive peak forward current $f > 15$ Hz ¹⁾	30	A
I_{FSM}	Peak forward surge current 50 Hz half sinus-wave ³⁾	180	A
i^2t	Rating for fusing, $t < 10$ ms ³⁾	162	A ² s
R_{thA}	Max. thermal resistance junction to ambient ¹⁾		K/W
R_{thL}	Max. thermal resistance junction to terminals ⁴⁾	5	K/W
T_j	Operating junction temperature	- 50 ... + 200	°C
T_s	Storage temperature	- 50 ... + 175	°C

Characteristics		$T_A = 25$ °C, unless otherwise specified	
Symbol	Conditions	Values	Units
I_R	Maximum leakage current, $T_j = 25$ °C; $V_R = V_{RRM}$	40	µA
	$T_j = 100$ °C; $V_R = V_{RRM}$	400	µA
C_J	Typical junction capacitance (at MHz and applied reverse voltage of V)	-	pF
Q_{rr}	Reverse recovery charge ($U_R = V$; $I_F = A$; $dI_F/dt = A/ms$)	-	µC
E_{RSM}	Non repetitive peak reverse avalanche energy ($I_R = mA$; $T_j = °C$; inductive load switched off)	-	mJ



SBH 820 ... SBH 845

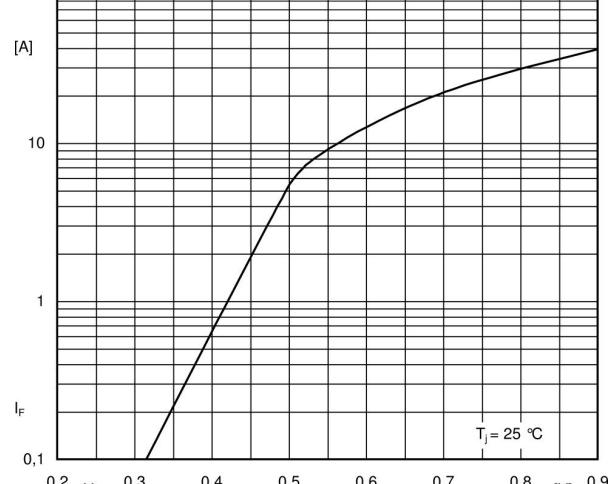


Fig. 1, Forward characteristics (typical values)

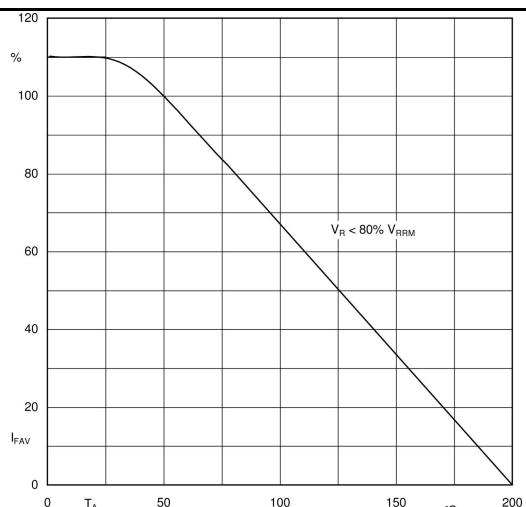


Fig. 2, Rated forward current vs. ambient temperature ¹⁾

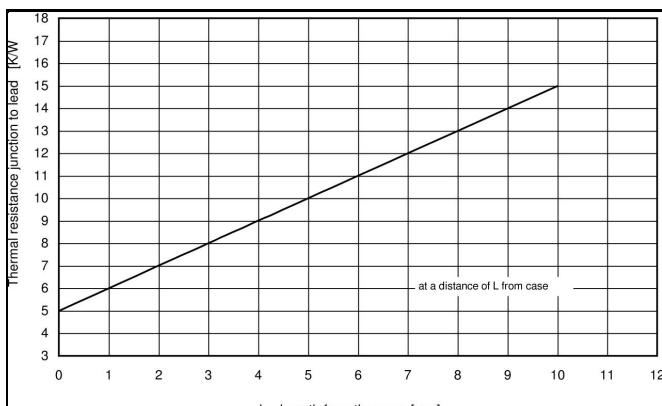


Fig. 3, Thermal resistance versus distance from case